

A FINNED DEVICE FOR REMOVING HEAT FROM AN
ELECTRONIC COMPONENT

ABSTRACT

5 A device for removing heat from an electronic component, comprising a
heat sink that can be coupled to the electronic component and conduct heat
therefrom. A finned appurtenance coupled to the heat sink can transfer the heat
into a fluid medium. The fins are oriented at an angle with respect to several flow
streams of the fluid medium across the fins. Each flow stream follows a unique
10 direction.